

58702

Product Information



50µm x-linkable polyurethane black HAF mounting tape

Product Description

tesa [®] XPU 58702 is a reactive mounting tape offering high bonding strength and elasticity after curing. This black double-sided tape has no backing. It is protected by a PE-coated paper liner. tesa [®] XPU 58702 is free of halogen according to IEC 61249-2-21 and compliant with current RoHS directive. At room temperature tesa [®] XPU 58702 is not tacky. It is activated by heat and pressure applied during the assembly process.

Special features:

- Extremely high bonding performance and reliability, even on thin design gaps
- · Excellent shock resistance
- · Extremely low oozing ratio
- · Black design

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Application Fields

tesa ® XPU 58702 is especially recommended for structural bonding of various substrates inside electronic devices:

- · Bonding of plastics
- · Bonding of metals
- Bonding of electronic components

Technical Information (average values)

The values in this section should be considered representative or typical only and should not be used for specification purposes.

Product Construction

•	Backing	none	•	Total thickness	50 μm
•	Type of adhesive	crosslinkable	•	Color	black

polyurethane

• Type of liner PE-coated paper



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Properties/Performance Values

• Bonding strength (push-out) 2.5 N/mm²

Additional Information

Technical recommendations:

tesa® XPU 58702 is not self-adhesive. It is activated by heat and pressure over a certain interval. The following values are recommendations for bond line parameters to start with.

Pre-lamination

During pre-lamination, laminate the adhesive tape onto the first component.

Setting:

Temperature¹ 55-65°C

Pressure² 3 bar

Time 5 – 20s

Short-time exposure to 65°C bond line temperature during pre-lamination does not affect the final bonding potential.

2. Bonding

Remove the liner from tape after the pre-lamination step. Position the second component.

Apply temperature and pressure for the bonding time to reach sufficient bonding strength.

- 2.1. PC/PC: Setting:
- Temperature¹ 80 140°C
- Pressure² 5 bar
- Time 10 120s
- 2.2. AL/PC: Setting:
- Temperature¹ 110 190°C
- Pressure² 5 bar



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Additional Information

• Time 20 – 120s

Short cycle times can be achieved at high bond line temperatures. For activation at low temperatures, increase the heat-press time. To reach maximum bonding strength, surfaces should be clean and dry. Allow at least 1-2 hours dwell-time after bonding before performance testing. Final bonding strength will be reached after 24 hours. Bonding strength values were obtained under standard laboratory conditions. PC/PC: bonding conditions: temperature = 110°C (120°C jig); pressure = 5 bar; time = 60 sec Storage: tesa® recommends storage in original packaging in cool and dry conditions.

Disclaimer

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